You are cordially invited to attend:

Advanced Packaging Technology Symposium

Wafer Level Packaging

2.5D and 3D Packaging

EMI Package Shielding

Power Packaging Technology

Wednesday, July 13, 2016 from 1:00 – 5:00PM
Conference Room 309 in the South Hall
Moscone Center
AGENDA

1:00 - 1:15 WELCOME
- Ruurd Boomsera CTO and Sr. VP Die Attach, BESI INC

1:15 - 2:15 WAFER LEVEL PACKAGING
- WLSIP - A Disruptive IoT Packaging Technology by Antonio Barry, Business Development Mgr, Nanium S.A.
- Next Generation Wafer Level Mold Technology by Jeroen Kleyburg, VP FICO Packaging, BESI INC

2:15 - 3:15 2.5D & 3D PACKAGING TRENDS
- Cost Effective 2.5D & 3D TCB Bonding Processes, Scalable to 20 & 10 um Pitch by Eric Beigne, Scientific Director Advanced Packaging and Interconnect, IMEC
- Advanced Die Attach Technology: Cost Effective Solutions for New Technology Trends by Dr. Hugo Pfeist, VP Technology Development, BESI INC

3:15 - 3:25 BREAK

3:25 - 4:10 EMI SHIELDING
- Panel and Wafer Level PVD Sputtering for Fan Out Processing - Challenges and Lessons Learned by Wilfried Bair, VP Business Development, Tongo Systems INC
- Singulation Solutions for Shielded Products by Jeroen Kleyburg, VP FICO Packaging, BESI INC

4:10 - 4:50 POWER PACKAGE TRENDS
- Argomax®, Sinter Technology: Superior Performance and High Speed Manufacturing by Mike March, VP Engineering Materials, Alpha Assembly Solutions
- Sintering Solutions by Dr. Hugo Pfeist, VP Technology Development, BESI INC

4:50 - 5:00 APPLE WATCH GIVE-AWAY

MODERATOR: Rene Hendriks, Sr. VP Sales North America and Europe, BESI INC